

2011 EDITORIAL CALENDAR

**2D/3D and DEVICE ASSEMBLY,
PACKAGING, INTERCONNECTS
and MATERIALS**

**WAFER-LEVEL PACKAGING
(WLP) BACK-END
PROCESSING**

**SHOW and CONFERENCE EXTRA
DISTRIBUTION**
(Bold denotes "Official Media Sponsor")

January/February

Space: Jan 7

Materials: Jan 14

- 3D Technology Trends
- Test & Burn-In Socket Advancements
- Copper Interconnect Solutions
- Bondtesting
- HDI Substrates
- Business Focus: Cost Analysis of Wire Bond, Flip Chip and TSV

- Handling Ultra-thin Wafers
- Wafer Cleaning Processes

- **BITS Workshop:** Mesa, AZ (Mar. 6-9)
- IMAPS Device Packaging Workshop: Scottsdale, AZ (Mar 7-10)
- Design, Automation and Test Europe (DATE), Grenoble, France (Mar 14-18)
- SEMICON China: Shanghai China (Mar 15-17)
- Meptec: Thermal Mgmt, San Jose, CA (Mar 21)

International Directory of Burn-in & Test Sockets

March/April

Space: Feb 25

Materials: Mar 4

- Dispense / Die Attach Materials
- Package Design Software
- Making MEMS More Cost Effective
- IC Packaging Foundry / OSATs Roundup
- Business Focus: Partnering with Suppliers

- Copper Pillar Bumping
- LED Packaging

- APEX Expo: Las Vegas, NV (Apr 12-14)
- SEMICON Singapore (May 10-12)
- Meptec: MEMS, San Jose, CA (May 19)

International Directory of IC Packaging Foundries

May/June

Space: Apr 22

Materials: Apr 29

- Thermal Management Solutions
- Package Reliability
- Flip Chip
- EDA Design Tools for 3D ICs
- Business Focus: Keeping Your Plant Up To Date

- Wafer Probing
- Die to Wafer Stacking for TSVs

- **ECTC/ITHERM:** Lake Buena Vista, FL (May 31-Jun 3)
- IEEE IITC: Burlingame, CA
- D43D 2011, Grenoble, France (Jun 28-29)

International Directory of Flip Chip Placement Systems
International Directory of Wafer Bumping Foundries

July/August

Space: Jun 10

Materials: Jun 17

- Signal Integrity in Package Design
- Encapsulation / Sealing
- 3D Standardization
- Final Test
- Advances in Printing for Electronic Devices
- Business Focus: Finding Bumping Expertise

- Metrology Processes for 3D ICs
- Via Formation

- SEMICON West: San Francisco (Jul 12-14)
- SEMICON Taiwan: Taipei, Taiwan (Sept 7-9)
- Meptec: Medical, Tempe, AZ (Sept 14-15)
- International Test Conference (ITC) Anaheim, CA (Sept 20-21)

International Directory of Automated Encapsulation Systems

September/October

Space: Aug 26

Materials: Sep 2

- Cost Reduction in Package Design
- Design for Test
- Medical Device Packaging
- Automotive Electronics Market Update
- Silicon Interposer Technology
- Known Good Die (KGD)

- WLP Testing

- **IWLPC – International Wafer-Level Packaging Conference Santa Clara, CA** (Oct 3-6)
- IMAPS: Long Beach, CA (Oct 9-13)
- SEMICON Europa Dresden, Germany (Oct 11-13)
- SMTAI: Ft Worth, TX (Oct 16-20)

International Directory of Automated Defect Inspection Systems

November/December

Space: Oct 26

Materials: Nov 2

- Reliability Design & Testing
- Evolving 3D IC Infrastructure
- Underfill / Encapsulation / Molding
- Solder Trends / Solder Ball Attach
- MEMS Packaging

- Wafer to Wafer Stacking Processes
- Wafer Dicing

- SEMICON Japan: Chiba, Japan (Dec 7-9)
- RTI 3D Systems Architecture Conference Burlingame, CA (TBD)
- Pan-Pac Microelectronics Symposium (TBD)

International Directory of Solder Sphere Suppliers